



Product Change Notification / JAON-14DJE704

Date:

16-Feb-2021

Product Category:

SONET/SDH/T1/E1 Devices

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4553 Initial Notice: Qualification of ATK as an additional assembly site for selected Microsemi products available in 896L BBGA (31x31x3.32 mm) package.

Affected CPNs:

[JAON-14DJE704_Affected_CPN_02162021.pdf](#)

[JAON-14DJE704_Affected_CPN_02162021.csv](#)

Notification Text:

PCN Status: Initial notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of ATK as an additional assembly site for selected Microsemi products available in 896L BBGA (31x31x3.32 mm) package.

Pre Change:

Assembled at STAK using WF3617 die attach, U8410-73C underfill, E679FGBR substrate core, WF6063M5 solder ball flux, and SE4450 thermal grease material.

Post Change:

Assembled at STAK using WF3617 die attach, U8410-73C underfill, E679FGBR substrate core, WF6063M5 solder ball flux,

and SE4450 thermal grease material, or Assembled at ATK using SCF5 die attach, NAU-27-1F (U8410-99-1F) underfill, E679FGR substrate core, SCF-3 solder ball flux, and DCL-5 thermal grease material.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	STATS CHIPPAC Korea LTD. (STAK)	STATS CHIPPAC Korea LTD. (STAK)	Amkor Technology Korea (K4), INC (ATK)
Bump material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag
Die attach material	WF3617	WF3617	SCF5
Underfill material	U8410-73C	U8410-73C	NAU-27-1F (U8410-99-1F)
Substrate core material	E679FGBR	E679FGBR	E679FGR
Solder ball Flux material	WF6063M5	WF6063M5	SCF-3
Thermal Grease material	SE4450	SE4450	DCL-5
Solder Ball Material	SAC305	SAC305	SAC305

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying ATK as an additional assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date: August 2021

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

[illegible]

Method to Identify Change: Traceability code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: February 16, 2021: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_JAON-14DJE704_Qual_Plan.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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